



Material Content Data Sheet



Sales Product Name				BSZ900N20NS3 G		Issued		25. September 2017	
MA#				MA000862686					
Package				PG-TSDSON-8-2		Weight*		40.20 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	1.835	4.56	4.56	45639	45639	
leadframe	inorganic material	phosphorus	7723-14-0	0.002	0.01		52		
	non noble metal	zinc	7440-66-6	0.008	0.02		209		
	non noble metal	iron	7439-89-6	0.168	0.42		4170		
wire	non noble metal	copper	7440-50-8	6.808	16.93	17.38	169328	173759	
	non noble metal	copper	7440-50-8	0.037	0.09	0.09	929	929	
	encapsulation	organic material	carbon black	1333-86-4	0.037	0.09		909	
	plastics	epoxy resin	-	1.882	4.68		46821		
	inorganic material	silicondioxide	60676-86-0	16.357	40.71	45.48	406841	454571	
leadfinish	non noble metal	tin	7440-31-5	0.387	0.96	0.96	9629	9629	
plating	noble metal	silver	7440-22-4	0.963	2.39	2.39	23942	23942	
solder	non noble metal	tin	7440-31-5	0.037	0.09		916		
	noble metal	silver	7440-22-4	0.046	0.11		1144		
	non noble metal	lead	7439-92-1	1.758	4.37	4.57	43717	45777	
heatspreader	inorganic material	phosphorus	7723-14-0	0.001	0.00		27		
	non noble metal	zinc	7440-66-6	0.004	0.01		107		
	non noble metal	iron	7439-89-6	0.086	0.21		2145		
heat sink CLIP	non noble metal	copper	7440-50-8	3.501	8.71	8.93	87085	89364	
	inorganic material	phosphorus	7723-14-0	0.002	0.00		47		
	non noble metal	zinc	7440-66-6	0.008	0.02		188		
	non noble metal	iron	7439-89-6	0.151	0.38		3753		
	non noble metal	copper	7440-50-8	6.127	15.24	15.64	152402	156390	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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